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Design and Integration of Flexible Electronic Materials/Devices

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Message from the Guest Editors

Flexible electronics have been actuated from the continuous development and progress in thin-film materials and devices. These advances have been further boosted by new integration strategies that enable the realizing of bendable, printable, stretchable, and low-cost electronic devices over large areas.

Over recent decades, flexible electronics have facilitated much of the technological innovation in the fields of transistors, LEDs, sensors, solar cells, substrates and functional materials, which have found applications on flexible displays, e-paper, RFID, solar cells, sensor arrays, biochips, and so on. This Special Issue focuses on the development of design and integration of flexible electronic devices, covers the main topics of (but is not limited to) new material theory and models, device structure and interface design, material preparations and device fabrications, device integrations and circuits, device testing and physical analysis, and large-area manufacturing processes.

Work on subjects other than the aforementioned that contribute to advancing knowledge of flexible electronics and their applications are also welcome in this Special Issue.



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Special Issue



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Message from the Editor-in-Chief

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